	Type	Hits	Search Text	DBs
1	BRS	11054	alignment near mark	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
2	BRS	661	257/797	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
3	BRS	97	257/797 and align$5 near (layers or films)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
4	BRS	564	257/797 not (257/797 and align$5 near (layers or films))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
5	BRS	66	257/797 and align$5 near (layers or films) and (integrated near circuit or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
6	BRS	0	257/797 and (align$5 near (layers or films) near (back)) and (integrated near circuit or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
7	BRS	6	alignment near mark and (align$5 near (layers or films) near (back)) and (integrated near circuit or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
8	BRS	31	alignment near mark and ((layers or films) near (back)) and (integrated near circuit or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
9	BRS	0	5817242.pn. and alignment near mark and ((layers or films) near (back)) and (integrated near circuit or IC)	USPAT; JPO
10	BRS	1	5817242.pn.	USPAT; JPO
11	BRS	1	5817242.pn. and alignment near mark	USPAT; JPO
12	BRS	0	5817242.pn. and alignment near mark and ((layers or films) near (back))	USPAT; JPO

	Type	Hits	Search Text	DBs
13	BRS	1	5817242.pn. and alignment near mark and ((layers or films)) and (integrated near circuit or IC)	USPAT; JPO
14	BRS	1569	alignment near mark and ((layers or films)) and (integrated near circuit or IC)	USPAT; JPO
15	BRS	11	(alignment near mark near (first near surface)) and ((layers or films)) and (integrated near circuit or IC)	USPAT; JPO
16	BRS	182	(alignment near mark near (first or front)) and ((layers or films)) and (integrated near circuit or IC)	USPAT; JPO
17	BRS	66	(alignment near mark near (first or front)) and ((layers or films) near (second or back or opposite)) and (integrated near circuit or IC)	USPAT; JPO
18	BRS	17	(alignment near mark near (first or front or top)) and ((layers or films) near (second or back or opposite or bottom) near surface) and (integrated near circuit or IC)	USPAT; JPO
19	BRS	36	(alignment near mark with (first or front or top) near surface) and ((layers or films) with (second or back or opposite or bottom) near surface) and (integrated near circuit or IC)	USPAT; JPO
20	BRS	0	(alignment near mark with (first or front or top) near surface) and (receiv$3 with (layers or films) with (second or back or opposite or bottom) near surface) and (integrated near circuit or IC)	USPAT; JPO
21	BRS	28	(alignment near mark with (first or front or top) near surface) and (form$3 with (layers or films) with (second or back or opposite or bottom) near surface) and (integrated near circuit or IC)	USPAT; JPO

	Type	Hits	Search Text	DBs
22	BRS	3	(alignment near mark with (first or front or top) near surface) and (form$3 with (integrated near circuit or IC) with (second or back or opposite or bottom) near surface)	USPAT; JPO
23	BRS	0	6309943.pn. and (alignment near mark) and printed and recess	USPAT; JPO
24	BRS	1	6309943.pn. and (alignment near mark) and printed	USPAT; JPO
25	BRS	4	(alignment near mark) near printed near substrate	USPAT; JPO
26	BRS	7	61156839.pn. or 5952247.pn. or 6013954.pn. or 5952694.pn. or 5754405.pn. or 6309943.pn. or 4423127.pn.	USPAT; JPO
27	BRS	154	257/798	USPAT
28	BRS	380	257/798	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB